

## MINUTES

### P-2.5 COMMITTEE FOR TANTALUM & NIOBIUM CAPACITORS

WEDNESDAY, September 26, 2007

2:00 to 4:00 PM

San Antonio, TX

#### 1. COMMITTEE ORGANIZATION AND PROCEDURES

##### 1.1 Membership and attendance

Membership and attendee list was updated.

##### 1.2 Review and approve agenda

Agenda accepted

##### 1.3 Approve minutes of last meeting, San Diego, April 18, 2007

Minutes accepted

##### 1.4 Correspondence

None

#### 2. OLD BUSINESS

##### 2.1 Reports

None

##### 2.1.1 Passive Component Steering Committee (S.1).....Mike Lauri (Announcement of future meeting dates and locations)

Dave to provide the S-1 with the presentation material presented during the Sept 25 meeting regarding the AEC Q-200 pre-conditioning.

##### 2.1.2 Government Specifications and Standards..... DSCC Representative

No updates.

##### 2.2 Surface Mount Tantalum Capacitors

Ralph to provide 535, 809, 717, 757, and 953 purchases for the past three years. Team would like to know if anyone is purchasing the standards from the P2.5 group.

**2.1 Status: Standard (EIA-535BAAC),**

**Will include NbO/MnO2/Polymer/Conformal/TAC/Alum. Will add Facedown in the standard. Suggest the new standard include the EIA 198 Format. The team will have a working group meeting in Charlotte on Nov 14-16<sup>th</sup> to draft a standard. Mike will take the 198 Spec and create a frame work structure for the working group.**

**2.1.2 Discussion of new case sizes, ratings, or products....All Members**

**Need to capture the lower profiles for all standard footprints. Will add to the 535 revision.**

**2.2.2.1 Lead-frame less/face down termination molded specification?**

**Face down terminations will be included in the 535 revision.**

**2.3 AEC Q 200 Preconditioning DOE project**

**Mary has presented the results of the preconditioning test. The item will be included in the AEC Q200 Agenda for November – April (meeting on Tuesdays) and will be further discussed at that time. Mary to report on the outcome during the Spring Summit.**

**2.4.1 Lead free solder topics - Tin Whiskers.....China RoHS update**

**No updates**

**2.5 Update EIA 809 Tantalum Applications Guide**

**This PN will be placed on hold pending the outcome of the 535 update.**

**2.6.1 Review existing specifications: J-Std-020C, IPC-9503 (MSL passives), IPC-9504 (Assembly Process Simulation for Non-IC Devices)**

**No updates**

**2.7 Review and update EIA list of "active working projects**

**No updates**

**2.8 Review Niobium/NbO draft specification/ PN number 5075**

**This PN will be placed on hold pending the outcome of the 535 update.**

**2.9 Update EIA IS 717 Qualification specification number PN 5097**

**Vote was made to sent the draft out for ballot. Vote was passed. PN5097 will go out for ballot. Jayson will send out to Dave.**

**3. NEW BUSINESS**

**3.1.1 Discuss addition if Aluminum Polymer caps to committee business**

**Aluminum Polymer will be captures with the 535 update as well.**

**3.2 Inputs for "All-Chairs Meeting"**

**4. ADJOURNMENT**